



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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CHO-BOND® 1016

ONE COMPONENT CORROSION RESISTANT ELECTRICALLY CONDUCTIVE SILICONE SEALANT



Customer Value Proposition:

CHO-BOND 1016 is a nickel-plated graphite filled, one-component conductive silicone specifically designed for use as a fillet, gap filler and seam sealant on electrical enclosures for EMI shielding or electrical grounding. Minimum recommended bond line for CHO-BOND 1016 is 0.007 inches. In addition, CHO-BOND 1016 may be used for EMI gasket repair, bonding, and attachment in applications where moderate lap shear strength (150 psi) is required. The nickel-plated graphite filler provides good galvanic corrosion resistance for applications with aluminum as the mating substrate. CHO-BOND 1016's moisture cure silicone polymer system allows it to cure to the touch in 24hrs and provides a flexible and resilient conductive and environmental seal over a wide range of application temperatures. CHO-BOND 1016's nickel-plated graphite filler offers good EMI shielding for enclosures where both RF fields must be excluded and internal radiated emissions attenuated.

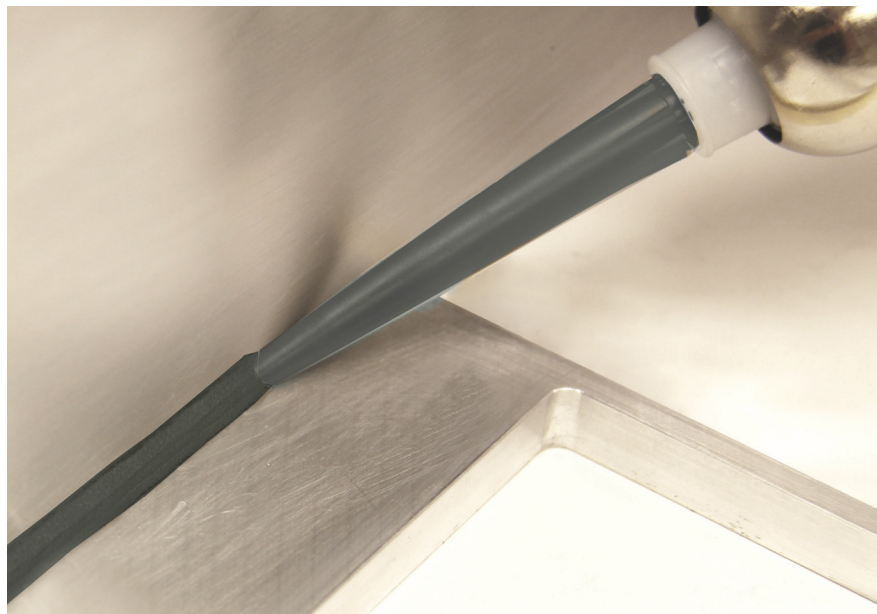
For best adhesion results, CHO-BOND 1016 should be used in conjunction with CHO-SHIELD 1086 primer. Typical applications include man portable electronics, radar and communication systems, EMI vents, military ground vehicles, and shelters.

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Features and Benefits:

- One component
- Nickel plated graphite filler
- No VOCs
- Moisture cure silicone
- Light weight
- Non corrosive cure mechanism
- Medium paste
- Easy to use, no weighing or mixing required.
- Moderate conductivity 0.500 ohm-cm, low cost (\$/cc), good galvanic corrosion resistance against aluminum substrates.
- Minimal shrinkage.
- 30 minute working life, rapid skin formation, 24 hr handling time, requires no pressure during curing, wide range of application temperatures. 1 week for full cure.
- More coverage per gram of material, minimal weight added to assembly or vehicle.
- No corrosive by-products generated during curing to damage substrate.
- Easy to dispense, apply and spread, can be used on overhead or vertical surfaces.



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CHO-BOND 1016 - Product Information

Table 1 Typical Properties

CHO-BOND 1016		
Typical Properties	Typical Values	Test Method
Polymer	Silicone	N/A
Filler	Nickel-Plated Graphite	N/A
Mix Ratio, A : B (by weight)	1-part	N/A
Color	Dark Gray	N/A (Q)
Consistency	Medium Paste	N/A (Q)
Maximum DC Volume Resistivity	0.500 ohm-cm	CHO-95-40-5555* (Q/C)
Minimum Lap Shear Strength**	150 psi (1034 kPa)	CHO-95-40-5300* (Q/C)
Minimum Peel Strength**	8.0 lb./inch (1401 N/m)	CHO-95-40-5302* (Q/C)
Specific Gravity	2.4	ASTM D792 (Q/C)
Hardness	80 Shore A	ASTM-D2240 (Q/C)
Continuous Use Temperature	- 55°C to 125°C [-67 °F to 257 °F]	N/A (Q)
Elevated Temperature Cure Cycle	None	N/A
Room Temperature Cure	1 week***	N/A (Q)
Working Life	0.5 hour	N/A (Q)
Shelf Life, unopened	6 months @ 25°C (77°F)	N/A (Q)
Minimum thickness recommended	0.010 in (0.25 mm)	N/A
Maximum thickness recommended	0.040 in (1.02 mm)	N/A
Volatile Organic Content (VOC)	0 g/l	Calculated
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	1250 in ² (8065 cm ²)	N/A
Theoretical Coverage - Length of an 1/8" Diameter Bead per Pound (454 grams)	80 feet (24.4 m)	N/A

Note: N/A - Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test

* This test Method is available from Parker Chomerics.

** Minimum values listed are based on using the CHO-SHIELD 1086 primer that typically comes bundled with the CHO-BOND.

*** Cure is sufficient for handling in 24 hours. Full specification properties are developed after 1 week (168 hours) at room temperature.

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 1016	71	1.5 fluid ounce aluminum foil tube	50-02-1016-0000	1086
	300	6 fluid ounce SEMCO cartridge	50-01-1016-0000	1086

Table 3 Primer Ordering Information

Product	Weight (grams)	Packaging	Part Number
CHO-BOND 1086	10	3 dram glass vial	50-10-1086-0000
	95	4 fluid ounce glass bottle	50-04-1086-0000
	375	1 pint can	50-01-1086-0000

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

www.chomerics.com

www.parker.com/chomerics

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TB 1135 EN January 2014



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